

CHIPRACK WINS FOR DOWTY ELECTRONIC COMPONENTS

CHIPRACK, the revolutionary new chip interconnection product developed by Dowty Electronic Interconnect, won a major design award sponsored by "Electronics Weekly" at the recent Internecon '85 exhibition. It was judged to be the most innovative electro-mechanical product of the year.

Brian Shorrock, Managing Director of Dowty Electronic Components Limited received the award from the opposition spokesman for Trade and Industry, John Smith, at the Internecon Awards Dinner in Brighton.

3D DESIGN

Chiprack was designed as a three-dimensional system for interconnecting very large scale integrated (V.L.S.I.) products packaged in the 'leadless chip' style. The system obviates the need for costly, custom designed, multilayer printed circuit boards by enabling complex three-dimensional interconnection patterns to be achieved within and between Chiprack structures.

Chiprack offers high packaging densities and was displayed as a functioning unit at the Intenecon '85 exhibition.

The product is at the pre-production stage and will be launched in production form

Brian Shorrock, Managing Director of Dowty Electronic Components Limited, receiving the award for the "Most Innovative Electro-mechanical Product of the Year" on behalf of DEI from the Opposition Spokesman for

Trade and Industry, John Smith (left), at the Internecon Awards Dinner in Brighton.

Looking on is Mike Elliott, Editor of "Electronics Weekly", which sponsored the award won by "Chiprack".



DOWTY Information Systems, part of Dowty Electronics Division,

Dowty launches into the consumer market

first
electronic

“Quattro is a best seller,” said Jones, General Manager of Quattro Information Systems. “It is a complete modem in a single package.”

ew Hayes-compatible Mu
nitition V22 bis Quattro Mode
ad already received advance ord
er 2,000 units, even before ord
er introduction at Compte 85.